

Soarch



Product Change Notification - KSRA-14MRKE725 (Convert To PDF)

Date:

27 Apr 2018

Product Category:

16-Bit - Microcontrollers and Digital Signal Controllers; 8-bit PIC Microcontrollers

Affected CPNs:



Notification subject:

CCB 3028 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu)bond wire in selected products of the 0.25um TSMC wafer technology available in 44L QFN package at NSEB assembly

Notification text:

PCN Status:

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 0.25um TSMC wafer technology available in 44L QFN package at NSEB assembly site.

Pre Change:

Using gold (Au) bond wire

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire

Pre and Post Change Summary:

	Pre Change	Post Change				
Assembly Site	NSEB Assembly Site	NSEB Assembly Site				
Wire material	Au Wire	CuPdAu Wire				
Die attach material	8600	8600				
Molding compound material	G700LTD	G700LTD				
Lead frame material	C194	C194				

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying CuPdAu bond wire at NSEB assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

May 27, 2018 (date code: 1821)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	July 2017				->	April 2018			May 2018						
Workweek	26	27	28	29	30		14	15	16	17	18	19	20	21	22
Initial PCN Issue Date				X											
Qual Report Availability										X					
Final PCN Issue Date										X					
Estimated Implementation Date														X	

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan

Revision History:

July 18, 2017: Issued initial notification.

April 27, 2018: Issued final notification. Attached the Qualification Report. Revised the affected parts list. Provided estimated first ship date on May 27, 2018.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN KSRA-22BMJF664 Qual Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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